	2/28/2013		PMP8906 REVB BOM			
Qty		Value	Description Control of the Control o	Size	Part Number	MFR
2	C16 C34	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
	C18 C33 C48 C52 C57 C59-					
17		0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
4	C17 C19 C24 C39	150pF	Capacitor, Ceramic, 50V, NPO, 5%	603	Std	Std
2	C21, C32	1800pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
_	C21, C32	180001	Capacitor, Ceramic, 30V, X/N, 10%	003	Stu	Stu
6	C13 C15 C35 C47 C51 C53	1uF	Capacitor, Ceramic, 25V, X7R, 10%	603	Std	Std
2	C58 C69	2200pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C64 C72	2700pF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
4	C49-50 C55-56	22pF	Capacitor, Ceramic, 50V, NPO, 10%	603	Std	Std
2	C74-75	3300pF	Capacitor, Ceramic, 100V, X7R, 10%	603	Std	Std
2	C20 C27	33pF	Capacitor, Ceramic, 50V, NPO, 10%	603	Std	Std
2	C22 C36	0.033uF	Capacitor, Ceramic, 50V, X7R, 10%	603	Std	Std
2	C5 C29	0.1uF	Capacitor, Ceramic, 100V, X7R, 20%	805	Std	Std
2	C26 C54	33uF	Capacitor, Ceramic, 10V, X5R, 10%	1206	Std	Std
2	C23 C31	4.7uF	Capacitor, Ceramic, 16V, X5R, 10%	1206	C3216X5R1C475KT	TDK
8	C1-4 C28 C43-44 C46	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	C3225X7R2A225K	TDK
8	C6-9 C25 C40-42	47uF	Capacitor, Ceramic, 16V, ±10%	1210	C3225X5R1C476M	TDK
2	C12 C30	4700pF	Capacitor, Ceramic, 2KV, X7R, 10%	1812	Std	AVX
2	C11 C45	open	Capacitor, Ceramic, 2KV, X7R, 10%	1812	Std	AVX
2	C14 C37	22uF	Capacitor, Alum, 22uF, 25V, 0.7 Ohms, 0.16A	0.217x 0.256"	EEVFK1E220R	Panasonic
2	C10 C38	150uF	Capacitor, Alum, 16V, 0.05 ohms, 1.8A, 20%	7343(D)	16TQC150MYF	Sanyo
4	D3 D5 D9 D11	BAS16LT1	Diode, Switching, 10-mA, 85-V, 350-mW	SOT23	BAS16LT1	Vishay
2	D6-7	BAT54S	Diode, Dual Schottky, 200-mA, 30-V	SOT23	BAS54S	Zetex
2	D10 D12	5.1V	Diode, Zener, 5.1V	SOD123	MMSZ5231BT1	On Semi
2	D2 D4	MURS120T3G	Diode, UltraFast, 1-A, 200-V	SMB	MURS120T3	On Semi
2	D1 D8	SBR30A45CTB	Diode, Dual Schottky, 30A, 45V	D2PAK	SBR30A45CTB	Diodes Inc.
4	J7-8 J10-11	PEC02SAAN	Header, Male 2-pin, 0.1"	0.1" x 2		Sullins
2	J6 J9	PEC04SAAN	Header, Male 4-pin, 100mil spacing	0.1" x 4		Sullins
2	L3-4	1mH	Inductor, CM Choke, 2A, ±30%	18.5 x 23.5mm	7446632001	Wurth
2	L1-2	0.33uH	Inductor, SMT, 0.33uH, 6.21A, 7.3 milliohm	0.300" sq	DR73-R33	Coiltronics
4	U2 U5 U11 U16	TCMT1107	IC, Photocoupler, CTR = 80% - 160%	MF4	TCMT1107	Vishay
	R5 R9 R21 R39 R42 R46					
8	R127-128	0	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R85 R106	140	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R84 R105	1.24K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R67 R91	1.5K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R2 R25	10	Resistor, Chip, 1/16-W, 1%	603	Std	Std
	R51 R54-55 R61 R63 R78-					
14	81 R99-102 R125	100K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
	R17 R23 R27 R45 R49 R75					
	R77 R83 R96 R98 R104					
	R108 R113-114 R117					
20	R122-124 R129 R130	10K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R82 R103	11.8K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R58 R64	110	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R7	13.7K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R76 R97	15K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R6 R40	16.9K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R14 R33	19.6K	Resistor, Chip, 1/16-W, 1%	603	Std	Std

	R8 R11 R31 R34 R52-53		1			
	R59-60 R109 R112 R118					
14	R121 R131-132	1K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
4	R68-69 R86-87	200	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R26	21K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R110 R119	249K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R72 R93		Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R48	open 24.3	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	1140	24.3	nesistor, Chip, 1/10-W, 1/6	003	Stu	Stu
6	R13 R16 R20 R28 R41 R43	2K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
4	R19 R35 R66 R90	3.01K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R70 R88	30.1	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R73 R94	30.1K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
4	R22 R47 R74 R95	35.7K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R15 R57	38.3	Resistor, Chip, 1/16-W, 1%	603	Std	Std
4	R12 R44 R107 R116	4.99K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R50	432	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R65 R89	499	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R111 R120	499K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
4	R24 R32 R71 R92	5.11K	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R115 R126	open	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R10	open	Resistor, Chip, 1/16-W, 1%	603	Std	Std
1	R36	open	Resistor, Chip, 1/16-W, 1%	603	Std	Std
2	R4 R38	20	Resistor, Chip, 1/10W, 5%	805	Std	Std
2	R3 R29	49.9K	Resistor, Chip, 1/10W, 5%	805	Std	Std
2	R56 R62	0.005	Resistor, Chip,1/2W, 1%	1210	Std	Std
2	R133-134	3.9	Resistor, Chip, 1/2 W, 5%	2010	ERJ14 series	Panasonic
2	R1 R37	40.2K	Resistor, Chip, 0.5 W, 5%	2010	Std	Std
2	R18 R30	0.18	Resistor, Chip, 0.22 Ohms, 1W, 5%	2512	Std	Std
1	J5	ED120/2DS	Terminal Block, 2-pin, 15-A, 5.1mm	0.40 x 0.35"	ED1514	OST
2	J1 J4	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25"	ED1514	OST
2	J3 J2	ED1514	Terminal Block, 2-pin, 6-A, 3.5mm	0.27" x 0.25"	ED1514	OST
	TP1 TP3 TP5-7 TP9-12					
20	TP16-23 TP25-27	5000	Test Point, Red, Thru Hole Color Keyed	0.1"x 0.1"	5000	Keystone
	TP2 TP4 TP8 TP13-15					
7	TP24	5001	Test Point, Black, Thru Hole Color Keyed	0.1"x 0.1"	5001	Keystone
2	Q2 Q5	BSC900N20NS3G	MOSFET, Nch, 200V, 90 milliohm, 9nC	PG-TDSON-8	BSC900N20NS3G	Infineon
	Q1 Q3-4 Q6-7 Q9-10 Q12-					
9	13	MMBT3904LT1G	Trans, NPN, 45V, 200mA, 200mW	SOT23	MMBT3904LT1	On Semi
2	Q8 Q11	MMBT3906LT1	Trans, PNP, 40V, 200mA, 200mW	SOT23	MMBT3906LT1	On Semi
4	U3-4 U12 U17	TL431AIDBZ	IC, Precision Adjustable Shunt Regulator	SOT23-3	TL431AIDBZ	TI
2	U1 U6	UCC3809-2	IC, Economy Primary-Side Controller	SO8	UCC3809D-2	TI
2	U9 U14	LM20CIM7	IC, Micro Temp Sensor, 2.4V, 10uA, 4%	SC70-5	LM20CIM7	TI
2	U10 U15	LM2901A	IC, Quad Comparator	TSSOP-14	LM2901AVQPWR	TI
2	U13 U18	LM2904AVQDR	IC, Dual Op-Amp	SO8	LM2904AVQDR	TI
2	U7-8	UCC29002DGK	IC, Load-Share Controller	MSOP-8	UCC29002DGK	TI
					PA3899NL	Pulse
2	T1-2	80 uH	Transformer, Custom	27.5 x33 mm	DCT25EFD-UxxS007	TDK

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